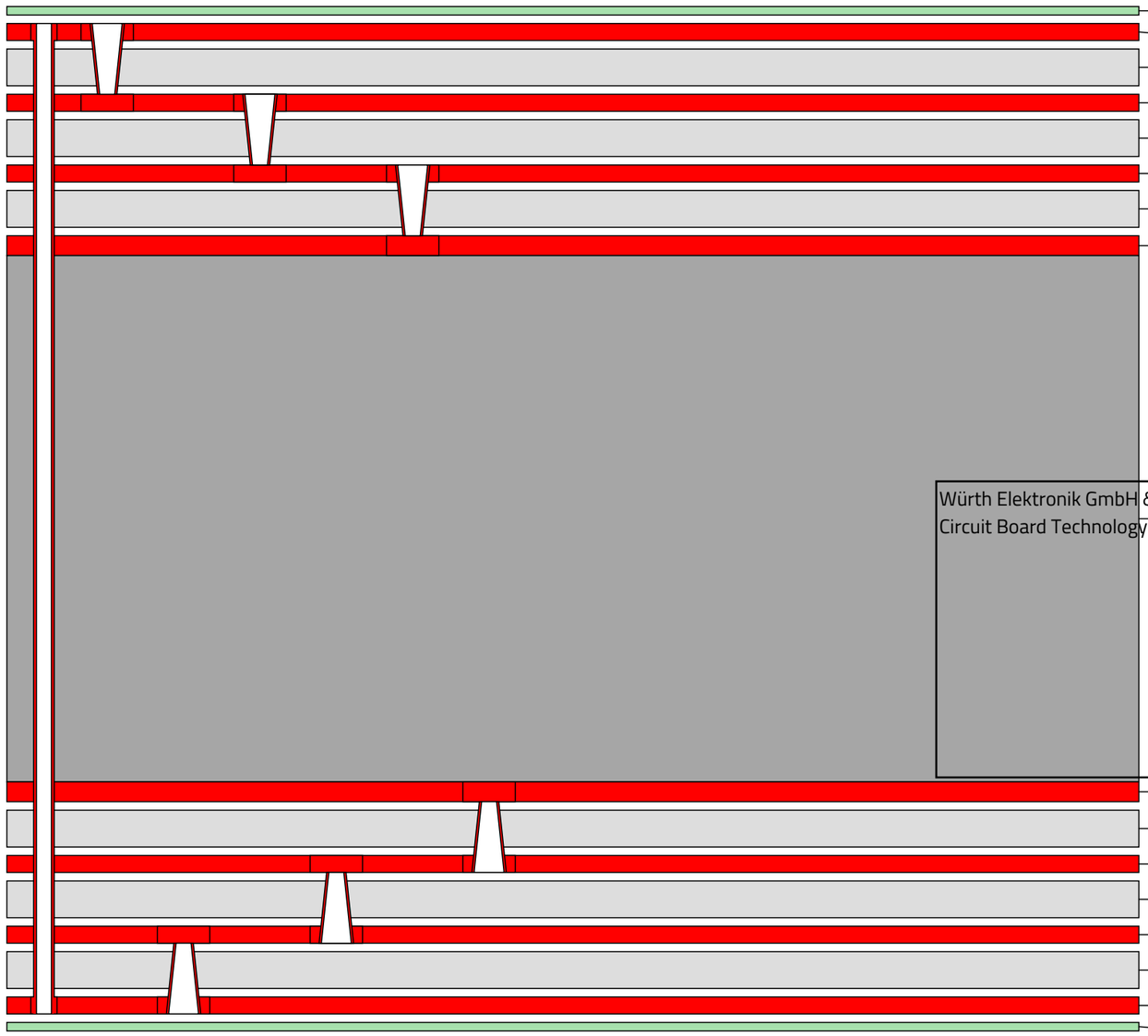

#	Layer	Thickness	Description	Dk	Df	Note
	Top Solder	0.015mm	Soldermask IPC-SM840	3,5	0,028	used on rigid parts
1	Top Side	0.030mm	Starting foil 1/4oz. after plating and processing			
		0.065mm	Prepreg IPC-4101/127/128	3,5	0,011	FR-4.1 filled, halogen free
2	Inner Layer 1	0.030mm	Starting foil 1/4oz. after plating and processing			
		0.065mm	Prepreg IPC-4101/127/128	3,5	0,011	FR-4.1 filled, halogen free
3	Inner Layer 2	0.030mm	Starting foil 1/4oz. after plating and processing			
		0.065mm	Prepreg IPC-4101/127/128	3,5	0,011	FR-4.1 filled, halogen free
4	Inner Layer 3	0.035mm	ED Base Copper			
		0.930mm	Core IPC-4101/127/128	5,1	0,011	FR-4.1 filled, halogen free
5	Inner Layer 4	0.035mm	ED Base Copper			
		0.065mm	Prepreg IPC-4101/127/128	3,5	0,011	FR-4.1 filled, halogen free
6	Inner Layer 5	0.030mm	Starting foil 1/4oz. after plating and processing			
		0.065mm	Prepreg IPC-4101/127/128	3,5	0,011	FR-4.1 filled, halogen free
7	Inner Layer 6	0.030mm	Starting foil 1/4oz. after plating and processing			
		0.065mm	Prepreg IPC-4101/127/128	3,5	0,011	FR-4.1 filled, halogen free
8	Bottom Side	0.030mm	Starting foil 1/4oz. after plating and processing			
	Bottom Solder	0.015mm	Soldermask IPC-SM840	3,5	0,028	used on rigid parts

Total thickness: 1.600mm

HDI8_3-2-3_1,60_35_V2.12

notes:

Final copper thickness according to IPC-6012

Please regard to our sectional design rules:
► www.we-online.com

PCB Thickness Tolerance: ± 10%

customer		created	
pcb name		approved	
engineer		format	A4, landscape
date			

Template Revision: 02/2021 by Andreas Schilpp / Michael Kress / Werner Öchslen

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